

GA35XCP12-247

IGBT/SiC Diode Co-pack

V _{CES}	=	1200 V
I _{CM}	=	35 A
$V_{\text{CE(SAT)}}$	=	3.0 V

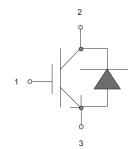
Features

- Optimal Punch Through (OPT) technology
- SiC freewheeling diode
- Positive temperature coefficient for easy paralleling
- Extremely fast switching speeds
- Temperature independent switching behavior of SiC rectifier
- Best RBSOA/SCSOA capability in the industry
- High junction temperature
- · Industry standard packaging

Package

RoHS Compliant





TO - 247AB

<u>Advantages</u>

- Industry's highest switching speeds
- High temperature operation
- Improved circuit efficiency
- Low switching losses

Applications

- Solar Inverters
- Aerospace Actuators
- Server Power Supplies
- Resonant Inverters > 100 kHz
- Inductive Heating
- Electronic Welders

Maximum Ratings, at T_i = 150 °C, unless otherwise specified

Parameter	Symbol	Conditions		Values		Unit
IGBT						
Collector-Emitter Voltage	V _{CES}		1200			V
DC-Collector Current	I _{CM}	T _c ≤ 105 °C	35			Α
Gate Emitter Peak Voltage	V_{GES}			± 20		V
Operating Temperature	T _{vi}		-40 to +150		0	°C
Storage Temperature	T _{stg}		-40 to +150		0	°C
Free-wheeling diode						
DC-Forward Current	I _F	T _c ≤ 105 °C	35			Α
Non Repetitive Peak Forward Current	I _{FM}	$T_c = 25 ^{\circ}\text{C}, t_p = 10 \mu\text{s}$	tbd			Α
Surge Non Repetitive Forward Current	I _{F,SM}	t_p = 10 ms, half sine, T_c = 25 °C	tbd			Α
Thermal Characteristics						
Th. Resistance Junction to Case	R_{thJC}	IGBT	0.34		K/W	
Th. Resistance Junction to Case	R _{thJC}	SiC diode	0.31 k		K/W	
Mechanical Properties				Values		
mechanical Froperties			min.	typ.	max.	
Mounting Torque	M _d		1.5		2	Nm



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Parameter	Symbol	Conditions	min.	typ.	max.	Unit
IGBT						
Gate Threshold Voltage	V _{GE(th)}	$V_{GE} = V_{CE}, I_{C} = 0.6 \text{ mA}, T_{i} = 25 ^{\circ}\text{C}$	5.5	6	6.5	V
Callastar Emittar Laglace Current	I _{CES.25}	$V_{GE} = 0 \text{ V}, V_{CE} = V_{CES}, T_j = 25 \text{ °C}$		0.02	0.2	mA
Collector-Emitter Leakage Current	I _{CES,150}	$V_{GE} = 0 \text{ V}, V_{CE} = V_{CES}, T_{i} = 150 ^{\circ}\text{C}$		0.3		mA
Gate-Leakage Current	I _{GES}	$V_{CE} = 0 \text{ V}, V_{GE} = 20 \text{ V}, T_j = 25 ^{\circ}\text{C}$			500	nA
Collector-Emitter Threshold Voltage	V _{CE(TO)}	T _j = 25°C		1.1		V
Collector-Emitter Slope Resistance	R _{CE,25}	V _{GE} = 15 V, T _j = 25 °C		50		mΩ
Collector-Emitter Slope Resistance	R _{CF.150}	$V_{GE} = 15 \text{ V}, T_{j} = 150 ^{\circ}\text{C}$		87.5		mΩ
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	$I_{\rm C} = 35 \text{ A}, V_{\rm GE} = 15 \text{ V}, T_{\rm j} = 25 ^{\circ}\text{C}(150 ^{\circ}\text{C})$		3.0(3.9)		V
Input Capacitance	U _{ioo}			tbd		nF
Output Capacitance	C	$V_{GE} = 0 \text{ V}, V_{CE} = 25 \text{ V}, f = 1 \text{ MHz}$		tbd		nF
Reverse Transfer Capacitance	C _{res}			tbd		nF
Gate Charge	Q _G	$V_{cc} = 800 \text{ V}, I_{c} = 35 \text{ A}, V_{ge} = 15 \text{ V}$		50		nC
Reverse Bias Safe Operating Area	RBSOA	T _i =125 °C, R _g =56Ω, V _{CC} =1200 V, V _{GE} =15 V		45		Α
Short Circuit Current	Isc	$T_{i} = 125 ^{\circ}\text{C}, R_{g} = 56\Omega,$		60		Α
Short Circuit Duration	t _{sc}	$V_{CC} = 900 \text{ V}, V_{GE} = \pm 15 \text{ V}$			10	μs
Rise Time	t,			85		ns
Fall Time	t,	V_{cc} = 800 V, I_{c} = 35 A,		205		ns
Turn On Delay Time	t _{d(on)}	$R_{\text{aon}} = R_{\text{aoff}} = 22 \Omega,$		40		ns
Turn Off Delay Time	t _{d(off)}	V _{GE(0n)} = 15 V, V _{GE(0ff)} = -8 V, T _j = 125 °C		232		ns
Turn-On Energy Loss Per Pulse	E			2.66		mJ
Turn-Off Energy Loss Per Pulse	E _{off}			4.35		mJ
Free-wheeling diode				•		
Forward Voltage	V_{F}	I _F = 35 A, V _{GE} = 0 V, T _j = 25 °C (150 °C)		2.6(3.5)		V
Threshold Voltage at Diode	V _{D(TO)}	T _i = 25 °C		0.8		V
Peak Reverse Recovery Current	Im	,		3.01		Α
Reverse Recovery Time	$I_{\rm rr} = 35 \text{ A}, V_{\rm GE} = 0 \text{ V}, V_{\rm R} = 650 \text{ V}$			36		ns
Diode peak rate of fall of reverse recovery current during tb	dl _{rr} /dt	-dI _F /dt = 300 A/µs, T _j = 125 °C		190		A/µs

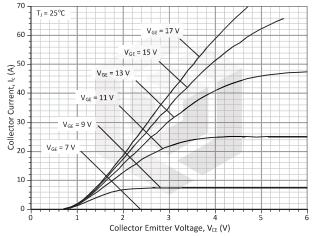


Figure 1: Typical Output Characteristics at 25 °C

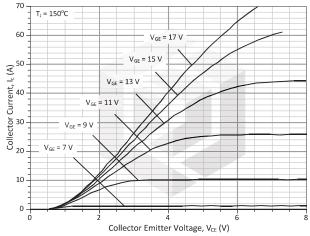


Figure 2: Typical Output Characteristics at 150 °C

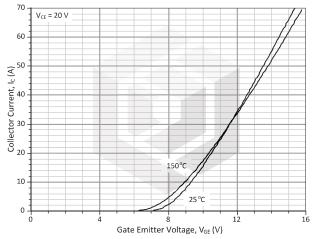


Figure 3: Typical Transfer Characteristics

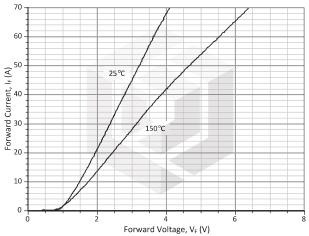


Figure 5: Typical FWD Forward Characteristics

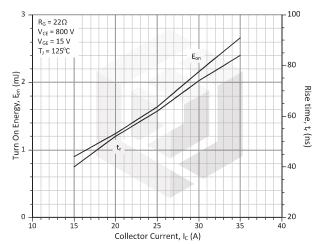


Figure 7: Typical Turn On Energy Losses and Switching Times

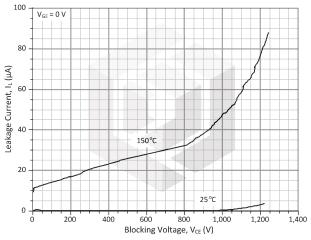


Figure 4: Typical Blocking Characteristics

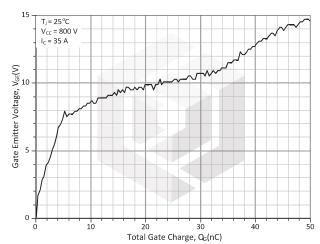


Figure 6: Typical Turn On Gate Charge

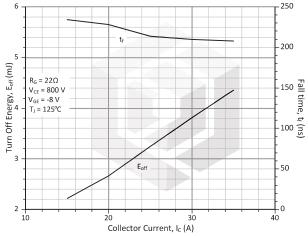


Figure 8: Typical Turn Off Energy Losses and Switching Times



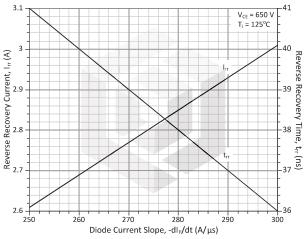
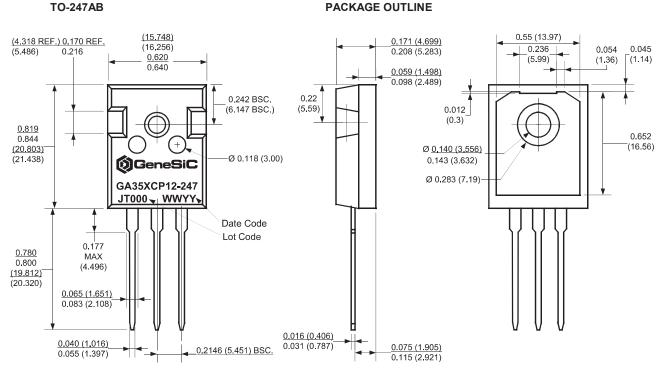


Figure 9: Typical Reverse Recovery Currents and Times

Package Dimensions:

PACKAGE OUTLINE



NOTE

- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
- 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS





Revision History					
Date	Revision	Comments	Supersedes		
2011/01/06	1	First generation release			

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